

PMEG6010CPA

60 V, 1 A low VF dual Schottky barrier rectifier

13 August 2026 Product data sheet

1. General description

Planar Schottky barrier rectifier in common cathode configuration with an integrated guard ring for stress protection, encapsulated in a SOT1061 leadless small Surface-Mounted Device (SMD) plastic package with medium power capability.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 1$ A
- Reverse voltage: $V_R \leq 60$ V
- Low forward voltage
- Exposed heat sink (cathode pad) for excellent thermal and electrical conductivity
- Leadless small SMD plastic package with medium power capability

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption applications
- Battery chargers for mobile equipment

4. Quick reference data

Table 1. Quick reference data

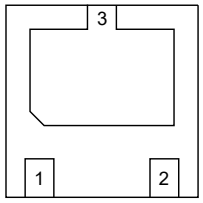
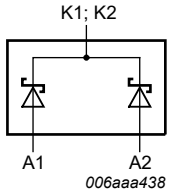
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per diode							
$I_{F(AV)}$	average forward current	square-wave pulse; δ = 0.5; f = 20 kHz; $T_{amb} \leq$ 110 °C	[1]	-	-	1	A
		square-wave pulse; δ = 0.5; f = 20 kHz; $T_{sp} \leq$ 140 °C		-	-	1	A
V_R	reverse voltage	$T_j \leq$ 25 °C		-	-	60	V
V_F	forward voltage	I_F = 1 A; T_j = 25 °C		-	490	540	mV
I_R	reverse current	V_R = 60 V; T_j = 25 °C		-	33	100	µA

[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3, standard footprint.

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5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode (diode 1)	 Transparent top view **DFN2020-3 (SOT1061)**	
2	A2	anode (diode 2)		
3	CC	common cathode		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG6010CPA	DFN2020-3	plastic, leadless thermal enhanced ultra thin small outline package; 3 terminals; 1.3 mm pitch; 2 mm x 2 mm x 0.65 mm body	SOT1061

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG6010CPA	AP

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8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
Per diode						
V_R	reverse voltage	$T_j \leq 25$ °C		-	60	V
$I_{F(AV)}$	average forward current	square-wave pulse; δ = 0.5; f = 20 kHz; $T_{amb} \leq 110$ °C	[1]	-	1	A
		square-wave pulse; δ = 0.5; f = 20 kHz; $T_{sp} \leq 140$ °C		-	1	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ ms; δ ≤ 0.25		-	7	A
I_{FSM}	non-repetitive peak forward current	square-wave pulse; t_p = 8 ms; $T_{j(init)}$ = 25 °C		-	9	A
Per device, one diode loaded						
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[2] [3]	-	500	mW
			[2] [4]	-	960	mW
			[2] [5]	-	1.8	W
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C

[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3, standard footprint.
[2] Reflow soldering is the only recommended soldering method.
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2.
[5] Device mounted on a ceramic PCB, Al_2O_3, standard footprint.

9. Thermal characteristics

Table 6. Thermal characteristics

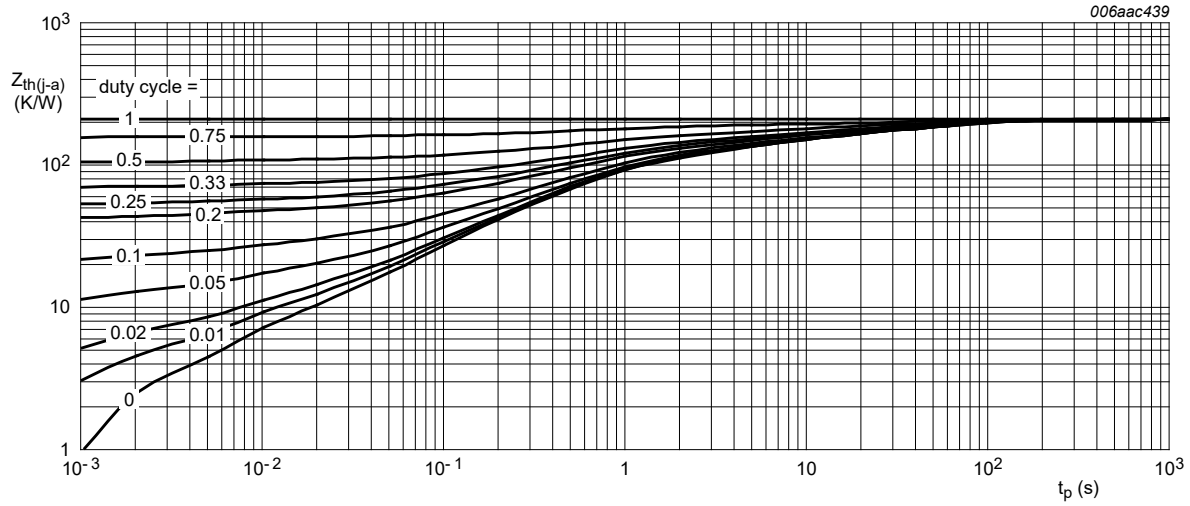
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2] [3]	-	-	250	K/W
			[1] [2] [4]	-	-	130	K/W
			[1] [2] [5]	-	-	70	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[6]	-	-	12	K/W

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
[2] Reflow soldering is the only recommended soldering method.
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2.
[5] Device mounted on a ceramic PCB, Al_2O_3, standard footprint.
[6] Soldering point of cathode tab.

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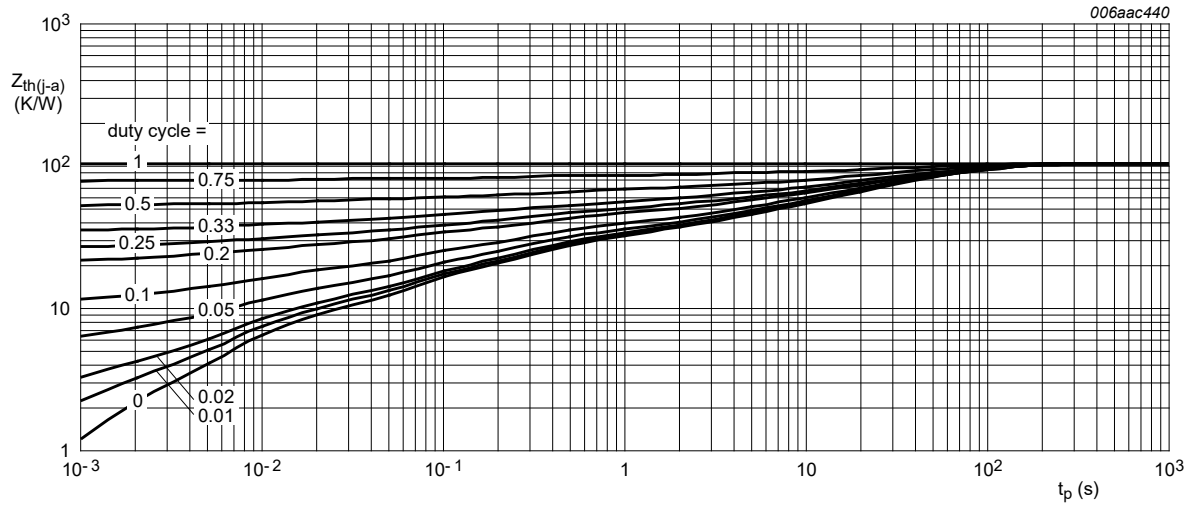
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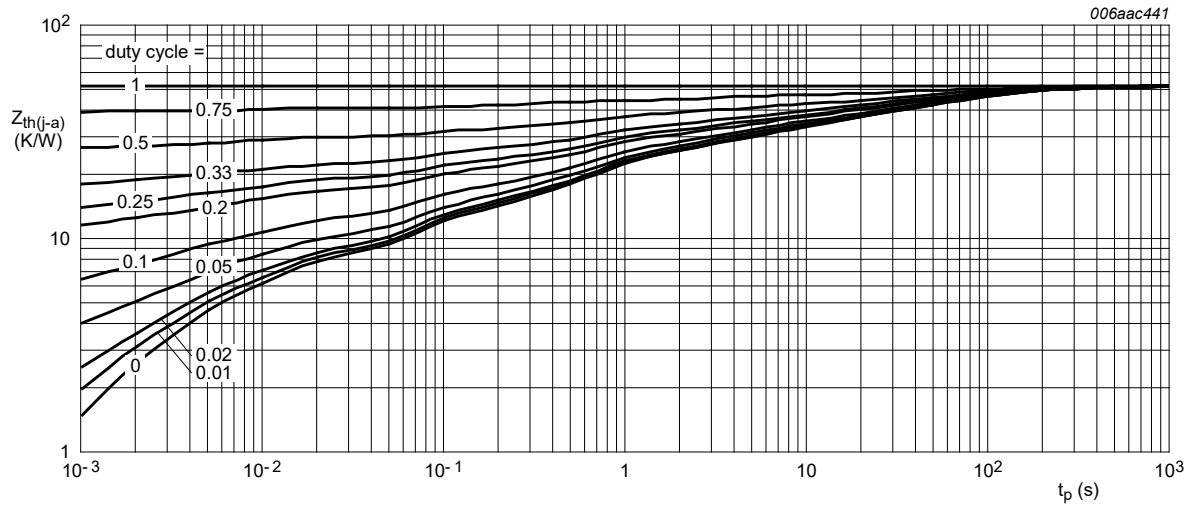
FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm^2

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al_2O_3, standard footprint

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

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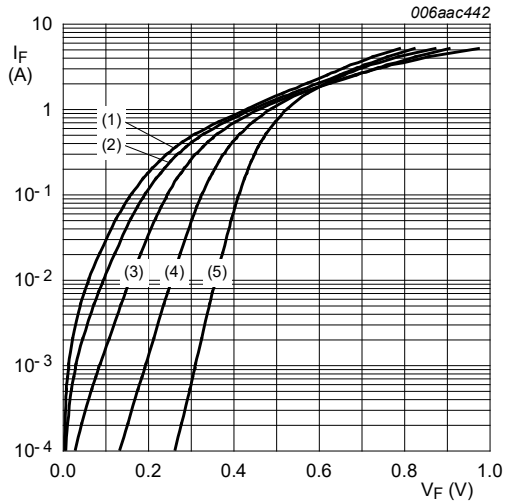
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10. Characteristics

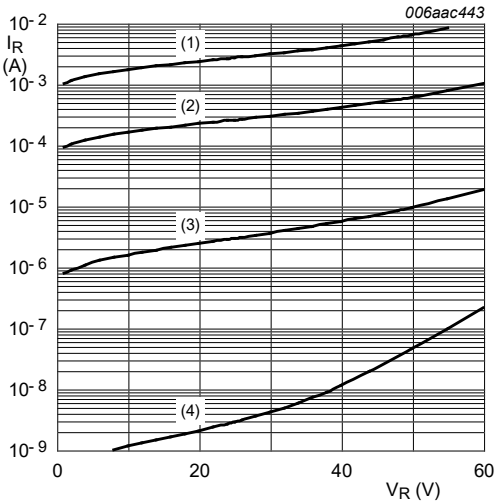
Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per diode							
V_F	forward voltage	I_F = 100 mA; T_j = 25 °C		-	325	-	mV
		I_F = 1 A; T_j = 25 °C		-	490	540	mV
I_R	reverse current	V_R = 10 V; T_j = 25 °C		-	2	-	µA
		V_R = 60 V; T_j = 25 °C		-	33	100	µA
C_d	diode capacitance	V_R = 1 V; f = 1 MHz; T_j = 25 °C		-	120	-	pF
		V_R = 10 V; f = 1 MHz; T_j = 25 °C		-	40	-	pF
t_{rr}	reverse recovery time	I_F = 10 mA; I_R = 10 mA; $I_{R(meas)}$ = 1 mA; R_L = 100 Ω; T_j = 25 °C		-	40	-	ns



(1) T_j = 150 °C
(2) T_j = 125 °C
(3) T_j = 85 °C
(4) T_j = 25 °C
(5) T_j = −40 °C

Fig. 4. Forward current as a function of forward voltage; typical values



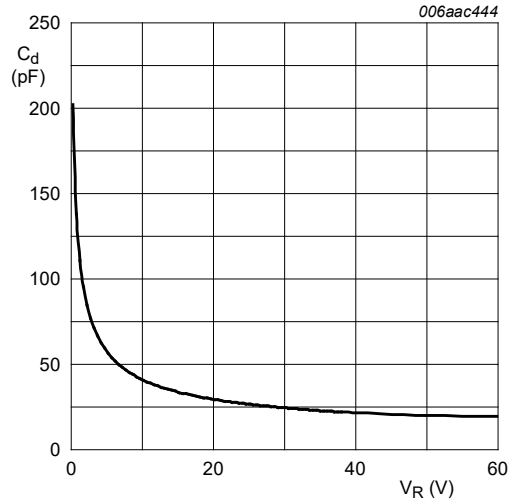
(1) T_j = 125 °C
(2) T_j = 85 °C
(3) T_j = 25 °C
(4) T_j = −40 °C

Fig. 5. Reverse current as a function of reverse voltage; typical values

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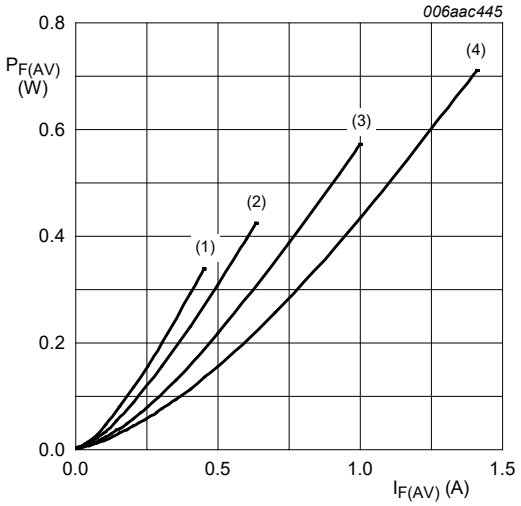
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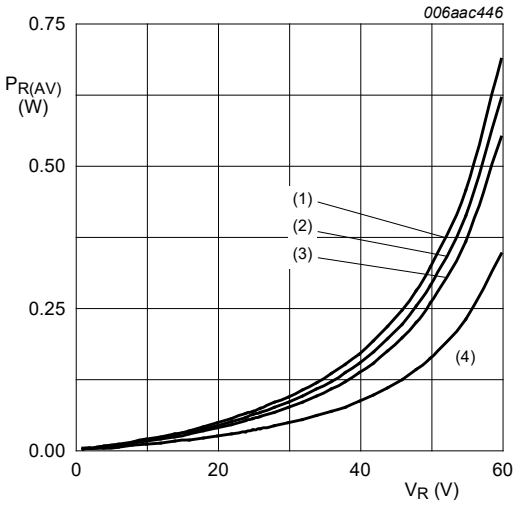
f = 1 MHz; T_{amb} = 25 °C

Fig. 6. Diode capacitance as a function of reverse voltage; typical values



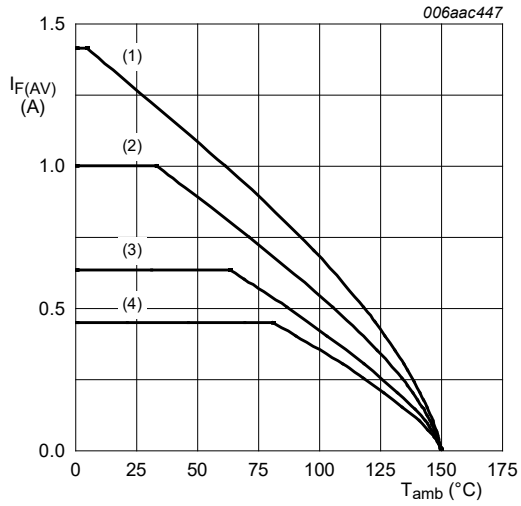
T_j = 150 °C
(1) δ = 0.1
(2) δ = 0.2
(3) δ = 0.5
(4) δ = 1

Fig. 7. Average forward power dissipation as a function of average forward current; typical values



T_j = 125 °C
(1) δ = 1
(2) δ = 0.9
(3) δ = 0.8
(4) δ = 0.5

Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values



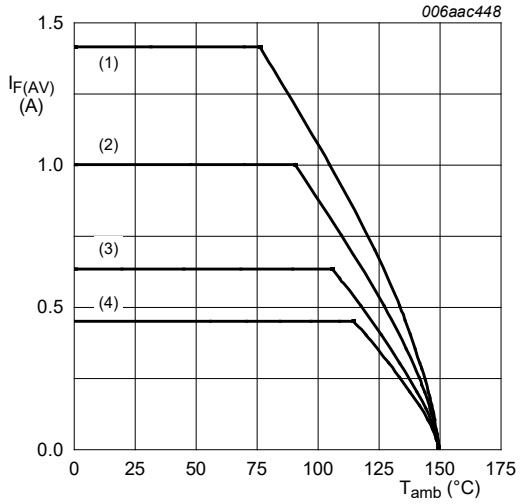
FR4 PCB, standard footprint
T_j = 150 °C
(1) δ = 1 (DC)
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values

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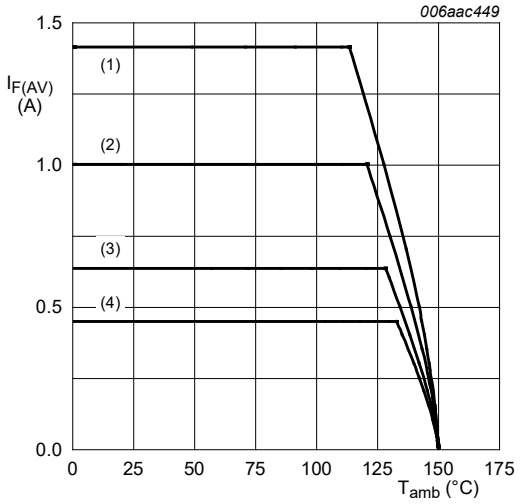
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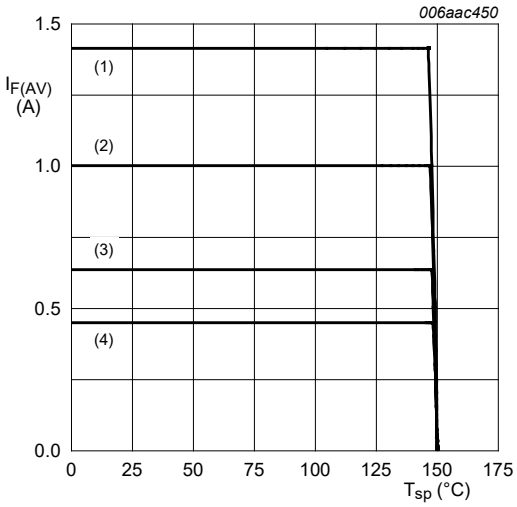
FR4 PCB, mounting pad for cathode 1 cm^2
T_j = 150 °C
(1) δ = 1 (DC)
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

Fig. 10. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al_2O_3, standard footprint
T_j = 150 °C
(1) δ = 1 (DC)
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

Fig. 11. Average forward current as a function of ambient temperature; typical values



T_j = 150 °C
(1) δ = 1 (DC)
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

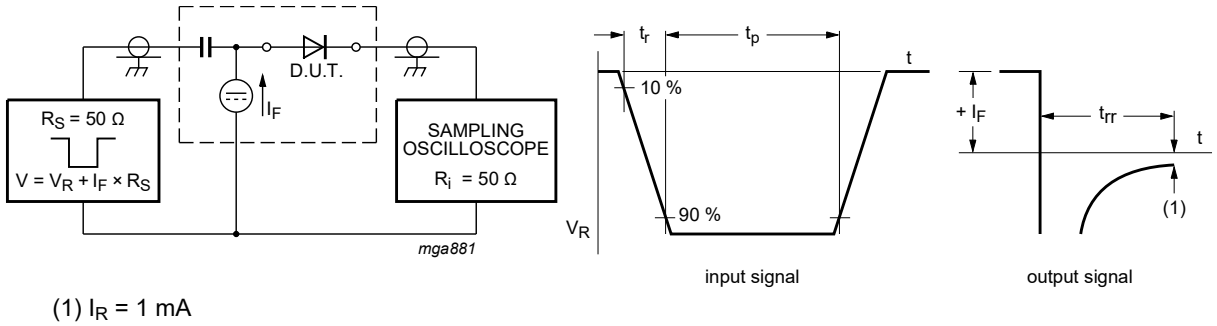
Fig. 12. Average forward current as a function of solder point temperature; typical values

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11. Test information



(1) I_R = 1 mA

Fig. 13. Reverse recovery time: test circuit and waveforms

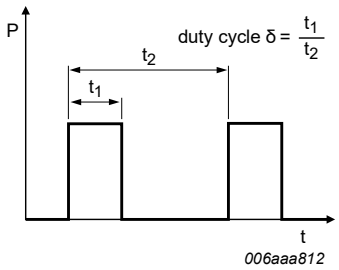


Fig. 14. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

$I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current

$I_{RMS} = I_{F(AV)}$ at DC

$I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current

12. Package outline

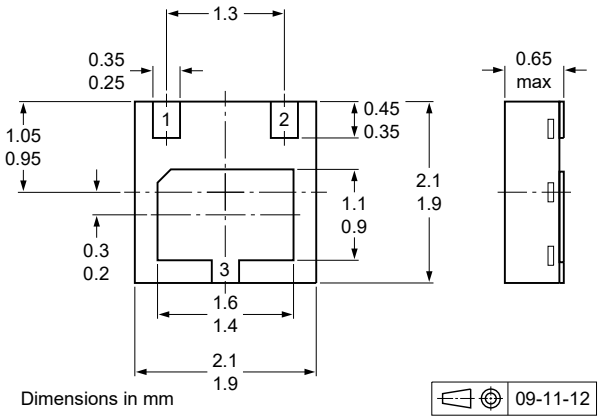


Fig. 15. Package outline DFN2020-3 (SOT1061)

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13. Soldering

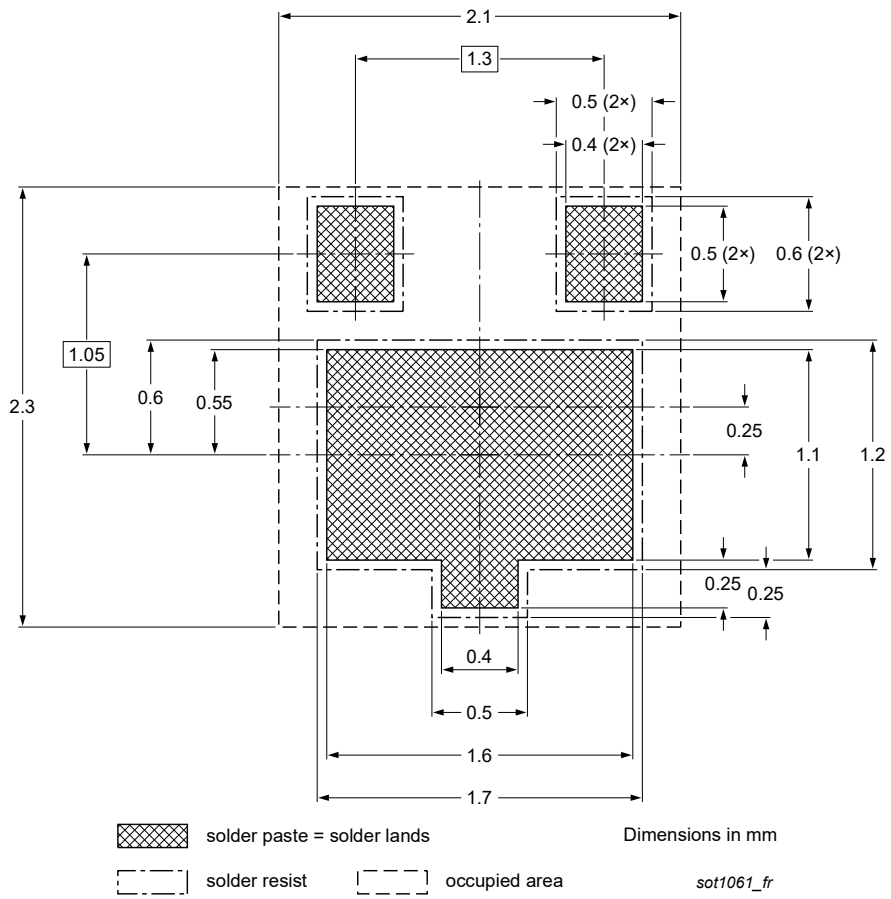


Fig. 16. Reflow soldering footprint for DFN2020-3 (SOT1061)

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14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG6010CPA v.3	20260813	Product data sheet	-	PMEG6010CPA v.2
Modifications:	• Product(s) changed to non-automotive qualification. Please refer to nexperia.com for automotive (-Q) product alternative(s).			
PMEG6010CPA v.2	20240910	Product data sheet	-	PMEG6010CPA v.1
PMEG6010CPA v.1	20100825	Product data sheet	-	-

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15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
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